ON Semiconductor

INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION
Generic Copy

---

05 Mar 2008

SUBJECT: ON Semiconductor Initial Product/Process Change Notification #16103

TITLE: Die replacement and Manufacturing flow change for ADP3120A, ADP3110A, ADP3118

PROPOSED FIRST SHIP DATE: 05 Jul 2008

AFFECTED CHANGE CATEGORY: Wafer Fab Process/Location; Assembly/Test Site Change

AFFECTED PRODUCT DIVISION: Computing Products Group

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact Sales Office or Sam Patel< Sam.Patel@onsemi.com >

NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change.

DESCRIPTION AND PURPOSE:

- ON Semiconductor has acquired the voltage regulation and thermal monitoring products (PTC) for computing applications from Analog Devices, Inc. Analog Devices will continue to provide the subject products for a limited time period.
- To eliminate supply constraints for the subject products and integrate product manufacturing flow into ON systems.
- The subject products will have change in die process technology and location as well as assembly/test locations. It is believed that the products will continue to meet the current device specifications and that functionally there will be no difference in performance, however samples may be requested at Final PCN issuance for verifications.

Initial Product/Process Change Notification #16103

QUALIFICATION PLAN:

Qualification is being performed to the following requirements (Process/Package Technology Qualification performed on NCP5359):
Actual Device Qualification will consist of:

Test Conditions	Sample Size	Duration
High Temp. Operating Life (HTOL) Ta=+125C, Bias	3x77	504, 1008 hrs
High Temperature Humidity Bias (HAST) 131C/85%RH	3x77	96 hrs
ESD – Human Body Model and Machine Model	1x30	
Latch Up Testing	1x10	
Electrical Characterization over Temperature	3x30	
Resistance to Solder Heat	3x30	

Package Qualification data already exists.

AFFECTED DEVICE LIST:

PART

ADP3110A0001RZR
ADP3110AKCPZ-RL
ADP3110AKRZ
ADP3110AKRZ-RL
ADP3118JCPZ-RL
ADP3118JRZ
ADP3118JRZ-RL
ADP3120AJCPZ-RL
ADP3120AJRZ
ADP3120AJRZ-RL